Embedded Solution





MIRO-3 (2 Layers)

DIN-Rail Mounted Embedded Series

Excellent heat-dissipating DIN-Rail mounted System

△ Application :

Facility monitoring / Automation control / Transportation

Technical Data:

Dimension 72.9 H x 178 W x 116D mm

Material Aluminum

Color Silver

Weight 1.5 Kg (Incl. M/B)

. Storage Space 1 x 2.5" HDD







CPU Type	M/B Model	VGA	DVI / HDMI /DP	сом	LAN	USB	Audio	Operation Temp SDDHDD
Intel® Skylake-U / Kaby Lake-U Core i CPU	3I610DW	N/A	HDMI, DP	2	5	4	DI/O, Nano SIM	70°C
Intel® Bat-Trail E3825 / E3845 / J1900	3I380A/CW	1	HDMI	4	2	4	Line out / Mic-in	70°C
Intel® Ivy Bridge 1047 UE 1.4GHz, i3, i7	3I847CW	1	DVI & HDMI	3	2	4	Line out / Mic-in	70°C
	31847NX	1	HDMI	2	1+4xPoE	3	Line out / Mic-in	70°C

More Functions								
3G / 4G	Wi-Fi	GPS	1 ~4 Video-IN					
Optional LAN	Parallel Port	COM	DIO					

The above available functions outline the possibility with system, for more information please contact us.

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